



# EWS300

## Microscopic Wafer Inspection



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## Highlight:

With years of research and development, the EWS300 was developed based on the decade of experience in automation process resulting in the development of our state of art product, with the groundbreaking features that bring the product to a new level of simplicity, reliability and speed for automatic optical inspection solution.

## SPECIFICATIONS

### INSPECTION

Inspection Capabilities	- Detecting wafer cosmetic defect, measurement, ink dot for wafer, probe mark & etc
Recipe / Setup (On and Off-Line)	- Automatic "golden die" image generation from production wafer. Interactive graphical tools for various zone definition. User-defined detection parameters per defects and zones.
Resolution	- Changeable with multiple lens, up to 0.35 $\mu$ m per pixel
Accuracy	- up to 0.7 $\mu$ m - Represents deviation between average of the distribution of results of repeated measurements of golden target and it certified value.
Repeatability	- up to 0.7 $\mu$ m at 3 sigma - Represents 3 sigma deviation value of the distribution of results of repeated measurements of the same real component.
Minimum Defect Detection	- up to 1 $\mu$ m

### SYSTEM CONFIGURATION

Factory Automation	- Secs/Gem
Cleanliness	- Class 100/1000
Particles removal system	- Hepa System

### WAFER HANDLING

Wafer ID	- Reading capability : SEMI M12, M13, M1.15, T1.95 - OCR - ECC200, T7 DtaMatrix, QR-Code - BC412, IBM412
Wafer Type	- Wafer & Film Frame Wafer
Supported Wafer Size	- 6", 8" & 12"
Wafer Cassettes	- Standard Cassettes: Entegris, Empak or Fluoroware (FOUP Optional)
Wafer Handling	- Twin Arms Wafer Robot with Slot Sensor (Mapping)

### OUTPUT

Output Data	- Wafer Map, SPC Analysis Report, KLARF
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### MACHINE LAYOUT

Dimension	- L1620 x W2235 x H1950mm
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